

Amendments to the Translated Specification:

Page 1, line 1, delete the heading reading:

~~Description~~

lines 5-8, amend the title as follows:

~~Title of the invention: Device for connecting the
terminal pins of a package for an optical
transmitting and/or receiving device to a printed
circuit board and conductor arrangement for such a
device.~~

DEVICE FOR CONNECTING THE TERMINAL PINS OF A
PACKAGE FOR AN OPTICAL TRANSMITTING AND/OR
RECEIVING DEVICE TO A PRINTED CIRCUIT BOARD AND
CONDUCTOR ARRANGEMENT FOR SUCH A DEVICE

above the first paragraph and below the title,
insert

-- Background of the Invention:

Field of the Invention: --.

delete line 19 as follows:

~~Background of the invention~~

Page 2, line 17, amend the heading as follows:

~~Object of the invention~~

Summary of the Invention:

delete the heading on line 29 as follows:

~~Summary of the invention~~

Page 6, lines 24-26, delete the paragraph as follows:

~~The invention is explained in more detail below on
the basis of an exemplary embodiment with reference
to the figures, in which:~~

Page 6, line 28 through page 7, line 12, amend the six
paragraphs as follows:

~~figure 1 shows a first perspective view of a device
with a TO package with a number of terminal pins
protruding from the base plate of the TO package and
a conductor arrangement for the contacting of the
terminal pins,~~

~~figure 2 shows a perspective view of the device of
figure 1 turned through 180°,~~

~~figure 3 shows the ground layer of the conductor
arrangement of figures 1 and 2,~~

~~figure 4 shows the high frequency side of the
conductor arrangement of figure 3,~~

~~figure 5 shows a perspective representation of the
conductor arrangement of figures 1 and 2 and~~

~~figure 6 shows an electro optical transducer with a
connecting device according to figures 1 and 2.~~

Fig. 1 is a perspective view of a device having a TO
package with a number of terminal pins protruding
from the base plate of the TO package and a conductor
arrangement for contacting the terminal pins;

Fig. 2 is a perspective view of the device of figure
1 turned through 180°;

Fig. 3 is a view of the ground layer of the conductor
arrangement of Figs. 1 and 2;

Fig. 4 is a view of the high-frequency side of the
conductor arrangement of Fig. 3;

Fig. 5 is a perspective view of the conductor
arrangement of Figs. 1 and 2;

Fig. 6 is a view of an electro-optical transducer
with a connecting device according to figures 1 and
2.

Page 7, line 14, amend the heading as follows:

~~"Description of a preferred exemplary embodiment"~~

Description of the Preferred Embodiments:

Page 8, line 25 through page 9, line 4, amend the
paragraph as follows:

Starting from the end region 63, the flexible
conductor fans out into two subregions, namely a
first central part 61 and a second, outer part 62,
which 61, 62, which are of different lengths and
different shapes. As can also be seen from figure 5,
the flexible conductor has in this case a first,
central part 62 and a second, outer part 61. The
central part 62 is of a relatively small length and
serves for the contacting of those terminal pins of
the base plate which are subjected to a high-
frequency signal. These are generally two of the
four terminal pins 41 to 44 represented in figures 1
and 2. In the exemplary embodiment presented, the
terminal pins 41, 42 are subjected to a high-

frequency signal. This is constituted, for example, by the two components of a differential driver signal or the outputs of a preamplifier coupled to a photodiode.

Page 12, lines 24-30, amend the paragraph as follows:

The actual connection of the T0 terminal pins ~~61 to~~ 41-44 to the pads 621, 622 or the via holes 73, 74 respectively takes place by means of a soldered connection, and so does the connection of the ground plate 5 to the ground contacting 71. It is pointed out that the actual interconnects cannot be seen in figures 1, 2 and 5, since in the configuration presented they are covered by solder resist.

Page 14, line top, replace the heading as follows:

~~Patent-claims~~ We Claim:

Page 19, please replace the abstract with the new abstract that is provided on the following separate page: